

## ABSTRACT

5 A substrate cutting apparatus for cutting a substrate  
includes a scribe line forming means for forming a scribe  
line on a substrate and a breaking means for breaking the  
substrate along the scribe line. The breaking means includes  
means for spraying a heated fluid having a temperature  
sufficient to cause expansion of the substrate onto the scribe  
line formed on the substrate so as to further extend a vertical  
10 crack extending from the scribe line in the thickness  
direction of the substrate.